CERTIFICATE OF ELECTRONIC FILING

I hereby certify that this correspondence is being filed electronically with the U.S. Patent and Trademark Office on the below date:

Date: March 9, 2011 Name: Jasper W. Dockrey, Reg. No. 33,868 Signature: /Jasper W. Dockrey/



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln. of: NGUYEN, et al.

Appln. No.:

10/577,175

Filed:

April 3, 2007

For:

METHOD FOR SELF-

SUPPORTED TRANSFER OF A FINE LAYER BY PULSATION AFTER IMPLANTATION OR CO-

IMPLANTATION

Attorney Docket No: 9905/40(BIF116533/US)

Examiner: Luke, Daniel M.

Art Unit: 2813

Confirmation No. 3451

DECLARATION UNDER 37 C.F.R. §1.131

Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Dear Sir:

Declarant, Christelle Lagahe-Blanchard, herby state as follows:

- 1. I have been a research scientist employed by the Commissariat à L'Energie Atomique ("the CEA") in particular in 2003 and 2004, and I am a named inventor of the above-referenced U.S. patent application.
- 2. Before August 28, 2003, I and the joint inventors, Nguyet-Phuong Nguyen and lan Cayrefource of S.O.I.TEC Silicon On Insulator Technologies S.A. ("Soitec") conceived the application of localized energy to the source substrate to provoke a catastrophic splitting of a thin film between the face of the source substrate and a buried weakened layer.



- 3. After conceiving the invention, I reported our invention to the Service Accords et Propriété Industrielle in the CEA, which is part of Direction de la Recherche Technologique located in Grenoble, France.
- 4. Before August 28, 2003, I received a draft French patent application prepared by French patent counsel at Rinuy, Santarelli in Paris. The French draft patent application that we received is attached hereto as Exhibit A. This draft French patent application was given to me by the joint inventors indentified above.
- 5. The draft French patent application has been translated into English and is attached hereto as Exhibit B. This draft French application describes the application of localized energy, for example in the form of a shock or pulse, to the source substrate to provoke a catastrophic splitting of a thin film between the face of the source substrate and a buried weakened layer.
- 6. After reviewing the draft patent application, I and the joint inventors made revisions to the draft patent application and I returned an edited version of the draft application to the Service Accords et Propriété Industrielle in Grenoble. After subsequent revisions made on September 25, 2003, a final version of the application was prepared as a French Patent Application by patent counsel at Rinuy, Santarelli. I received a letter from Ms. Corinne Vedel of the Service Accords et Propriété Industrielle informing me that the patent application was filed in the French Patent Office on October 28, 2003. The French Patent Office designated this application as French Patent Application No. 0312621. A copy of this French patent application is attached hereto as Exhibit C.
- 7. The above-referenced U.S. application is a U.S. nationalization of PCT Application No. PCT/FR04/02779, which, in turn, claims national priority to the French Patent Application No. 0312621, identified in paragraph 6 above. The French Patent Application No. 0312621 names myself, Nguyet-Phuong Nguyen, and Ian Cayrefourcq

as inventors. Prior to filing the PCT application referred to herein, additional subject matter was included and the additional inventors were named in the PCT application. These additional inventors as also named in the above-referenced U.S. application.

8. I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code.

Christelle Lagahe-Blanchard

14/10/10 Date